



10/685,872

Ifw

November 15, 2006

To: Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Fr: Stephen B. Ackerman, Reg. No. 37,761  
28 Davis Avenue  
Poughkeepsie, N.Y. 12603

Subject:

Serial No.	10/685,872	10/15/02
M.S. LIN ET AL		
"POST PASSIVATION INTERCONNECTION SCHEMES ON TOP OF THE IC CHIPS"		
Group Art Unit: 2822	KEVIN M. PICARDAT	

### SECOND PRELIMINARY AMENDMENT


Dear Sir:

Please enter this second preliminary amendment for the above-identified application for patent as follows:

### CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 16, 2006.

Stephen B. Ackerman, Reg. No. 37,761

Signature   
Date 11/16/06

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Claims are reflected in the listing of the Claims which begins on page 14 of this paper.

Amendments to the Drawings begin on page 24 of this paper and include an attached replacement sheet.

Remarks/Arguments begin on page 27 of this paper.

An Appendix including amended drawing figures is attached following page 28 of this paper.